Report on the Activities of the Association in the 14th Term

Presented by:
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EtherNet/IP™

Workshops
- North America (6X)
- Europe (4X)

PlugFests held
- North America (2X)
- Europe (1X)

Introductory Seminar
- Japan (3X)

Design & Development Seminar
- Japan (8)
Webinar in China

More than 400 Persons Were Introduced to ODVA by “Skylar”
EtherNet/IP Seminars

The Proven & Complete Solution

- Chengdu (China)
- Minneapolis
- Chicago
- Copenhagen
- Dallas
- Detroit
- Frankfurt
- Kolding (Denmark)
- Paris
- Philadelphia
- Seoul (2X)
- Shanghai
Tradeshows

- AIMEX – Korea (2X)
- Hannover Fair – Germany (2X)
- SPS/IPC/Drives Show – Germany (1X)
CIP Advantage Seminars

CIP™ College on Tour in Japan

- Hiroshima (2X)
- Kyoto
- Kanazawa
- Kumamoto
- Nagoya (2X)
- Omiya
- Tokyo
Forums in China

- Beijing “The CIP Forum”
- Shanghai “The CIP Forum”
- Shanghai “Development and Existence – Smart & Sustainable Manufacturing”

Representative from the United Nations Environment Program (UNEP) - Institute for Environment and Sustainable Development at Tongji University
General Session and Annual Meeting of Members  
2011 ODVA Industry Conference & 14th Annual Meeting  
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www.odva.org
The ODVA Specifications

- Four Publication Cycles
- More than 100 Enhancements

Publication Cycle
2X Per Year
Report on the Technical Activities of ODVA

- Organization and Roles
- Key Activities
- The Challenges Ahead
Introducing the TRB

- New principal member Bosch Rexroth
  - TRB representative will be added
- Returning principal member representatives
  - Rudy Belliardi (Schneider)
  - Paul Didier (Cisco)
  - Jeff Jurs (Omron)
  - Dave VanGompel (Rockwell)
- Membership elected representatives
  - Jörgen Palmhager (HMS)
  - Damien Leterrier (Molex)
- ODVA / Conformance Authority
  - Alain Grenier
Special Interest Groups

• Added Two New Special Interest Groups:
  - Rail Transport SIG
  - Energy Applications SIG

• Other Active SIGs:
  - CIP System Architecture
  - EtherNet/IP Infrastructure
  - DeviceNet™ Physical Layer
  - CIP Safety™
  - Conformance
  - Semiconductor

• EtherNet/IP Workshop
TRB Organization and work flow

- EtherNet/IP Workshop
- Special Interest Group
- Set SIG Work Plans
- Submit SE or TDE
- Technical Review Board
- Approved SE or TDE
- ODVA Staff (Conformance Authority)
- Update
- Update (TRB review)
- Conformance Tests
- Policies and Procedures
- Specifications Set
- Update

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Key Activities: Advancing Industrial Ethernet

► Extending *The EtherNet/IP Specification*
  ► EtherNet/IP QuickConnect™ (released)
  ► IP address conflict detection (released)
  ► Fiber optic sealed connectors (released)
  ► Profile for an EtherNet/IP infrastructure switch (underway)

► Providing Industry Thought Leadership
  ► EtherNet/IP performance testing
  ► Security white paper
  ► Device Level Ring white paper
  ► Updating planning and installation guide (in process)
Key Activities: Advancing Integrated Safety

- Extending *The CIP Safety Specification*
  - Analog safety device profile
  - Supporting analog safety objects

- Introduced linkages to SERCOS III
  - CIP functionality to implement CIP Safety in SERCOS devices
  - SERCOS functionality to support I/O and message connections
Key Activities: Advancing Integrated Motion

- Enhancing CIP Motion™ Objects
  - Updated Time Sync Object (Released)
  - Enhanced Axis object (Released)
  - Enhanced Motion Device Profile (Released)
  - Add Motion Controller object (Underway)
  - CIP to SERCOS gateway for motion control (Underway)
Key Activities: Extending Markets

- Energy management
  - Improve Awareness (Energy Objects: Underway)
  - Improve Efficiency (Phase 2)
  - Enable Profitable Transactions (Phase 3)

- Railway Application
  - Define applicable device profiles (Underway)
  - Identify Infrastructure enhancements (Underway)
Key Activities:
Maintaining “Gold Standard” of Conformance

► Maintain Conformance Test suites
  ► Updates to EtherNet/IP conformance tests (now at CT8)
  ► Updates to DeviceNet conformance tests (CT23)
► Developing test plan extensions
  • DLR Test Plan
  • Position Sensor Object Test Plan
  • CIP Sync™ Test Plan
  • QoS Test Plan
  • CIP Motion Test Plan
  • Multi-port Functionality Test Plan
  • Connection Configuration Object Test plan
  • Originator/Scanner Test Plan
Challenges Ahead

- We face key challenges individually and collectively:
  - Addressing new market opportunities
    - Adjacent Market Spaces:
      - Energy management / alternative energy
    - Global shifts in manufacturing base
      - ODVA is proactively working to make your investment in CIP technologies pay off
  - Increasing user needs and expectations
    - Increasing performance and scale of applications
    - Rapid and robust deployment
    - Latest technologies
      - ODVA continuously enhances specification set, user white papers and conformance capabilities
  - Keep pace with technology change
    - Rapidly evolving internet technologies (infrastructure / wireless/ IPV6)
      - ODVA provide a technical community and guidance to help you make your products better
Press Releases
February 7, 2011; March 3, 2011

The result of a lengthy investigation by ODVA and its leadership into the energy needs of industry, combined with the strong interest by ODVA members to support the sustainability objectives of manufacturers.
ODVA's energy approach will offer broad situational awareness of energy consumption and enable control strategies to optimize energy usage throughout the industrial ecosystem from the plant floor to the grid.
Start Investigating

The OEU-enabled™ Asset
Users will realize significant benefits in increased availability of ODVA-compliant products under the Rexroth brand, especially those implementing the EtherNet/IP network.